

Preliminary Amendment

Applicant: Michael Bauer, et al.
Serial No.: Not yet assigned
(Priority Application No. 10 2004 008 135.2)
(International Application No. PCT/DE2005/000215)
Filed: Herewith
(Priority Date: 18 February 2004)
(International Filing Date: 9 February 2005)
Docket No.: I431.170.101/FIN561PCT/US
Title: SEMICONDUCTOR COMPONENT HAVING A STACK OF SEMICONDUCTOR CHIPS AND
METHOD FOR PRODUCING THE SAME (as amended)

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

**SEMICONDUCTOR COMPONENT COMPRISING ~~HAVING~~ A STACK OF
SEMICONDUCTOR CHIPS AND METHOD FOR PRODUCING THE SAME**

The invention relates to a semiconductor component (14) comprising including a
stack (100) of semiconductor chips (1, 2), the semiconductor chips (1, 2) being fixed
cohesively one on top of another, is disclosed. The contact areas (5) of the semiconductor
chips (1, 2) are led as far as the edges (6) of the semiconductor chips (1, 2) and conductor
portions (7) extend at least from an upper edge (8) to a lower edge (9) of the edge sides (10)
of the semiconductor chips (1, 2) in order to electrically connect the contact area (5) of the
stacked semiconductor chips (1, 2) to one another.

[Figure 1]